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November 2, 2004

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

### Certificate

NOV 09 2004

### of Correction

Re: U.S. Patent Application for:  
"MULTI-CHIP MODULE"  
Serial No. 09/936962; Filed December 27, 2001  
Patent No. 6788546; Issued September 7, 2004  
First Named Inventor: Philippe Steiert et al.  
Our Reference No. FRR-12671

Dear Sir/Madam:

A Certificate of Correction under 35 U.S.C. 254 is hereby requested to correct Patent Office printing errors in the above-identified patent. Enclosed herewith is a proposed Certificate of Correction (Form No. PTO/SB/44) for consideration.

It is requested that the Certificate of Correction be completed and mailed at an early date to the undersigned attorney of record. The proposed corrections are obvious ones and do not in any way change the sense of the application.

We understand that a check is not required since the errors were on the part of the Patent and Trademark Office in printing the patent.

Very truly yours,

David E. Spaw, Reg. No. 34732

DES:ps  
Enclosure

NOV 17 2004

**UNITED STATES PATENT AND TRADEMARK OFFICE  
CERTIFICATE OF CORRECTION**

Page 1 of 1

PATENT NO. : 6,788,546 B1  
DATED : September 7, 2004  
INVENTOR(S) : Phillipe Steiert et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**Title Page:**

Replace entire abstract with the following abstract:

--A multi-chip-module includes a base carrier on which signal conductor tracks and signal contact surfaces arranged at least in a single layer are located, and with a semiconductor component operating in the signal range and connected with the signal conductor track and signal contact surfaces. A high degree of integration is achieved with a multi-chip-module of this type. In some areas on the base carrier power conductor tracks and power contact surfaces arranged in at least one layer are located. Furthermore, at least one power electronics component, operating in the power range, is provided, which is connected with at least one power conductor track, at least one power contact surface and at least one signal conductor track. The power conductor tracks have a larger cross section than the signal conductor tracks at least on the basis of greater thickness dimensions.--

**MAILING ADDRESS OF SENDER:**

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PATENT NO. 6,788,546

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This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Attention Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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